

UP SuperServer SYS-111C-NR

1U UP CloudDC with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 slots + 2 PCIe 5.0 AIOM slots



More details here

Key Applications

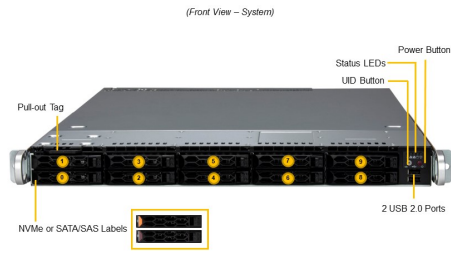
Virtualization, HPC, CDN, Edge Nodes, Cloud Computing, Data Center
Optimized, Storage Headnode,

Key Features

- Single Socket E (LGA-4677) 4th/5th Gen Intel® Xeon® Scalable processors. Up to 350W TDP;
- Intel® C741 Chipset;
- 16 DIMMs; Supports 3DS DDR5 RDIMM. Up to 5600 MHz;
- Dual AIOM (OCP 3.0) for networking (NCSI available), 1 dedicated IPMI LAN;
- 10x front hot-swap 2.5" SATA3 drive bays (Optional all 10 hybrid Gen5 NVMe), SAS3 with additional SAS controller card;
- Redundant Now Titanium 860W Power Supplies;

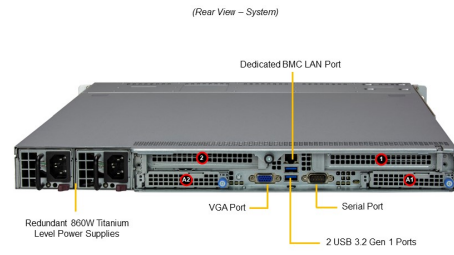


Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 605 x 197 x 822mm (23.8" x 7.8" x 32.4")
Processor	Single Socket E (LGA-4677) 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors Up to 64C/128T; Up to 320MB Cache
GPU	Max GPU Count: Up to 2 single-width GPU(s) Supported GPU: NVIDIA PCIe: T1000, L4, A2 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect
System Memory	Slot Count: 16 DIMM slots/8 Channels Max Memory (1DPC): Up to 2TB 5600MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 4TB 4400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 10 bay(s) • 10 front hot-swap 2.5" PCIe 5.0 NVMe*/SAS*/SATA drive bay(s) (*NVMe/SAS support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 PCIe 3.0 x2 NVMe slot(s) (M-key 2280/22110)
Expansion Slots	Default • 2 PCIe 5.0 x16 FHHL slot(s) • 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
On-Board Devices	SATA: SATA (6Gbps) ; RAID 0/1/5/10 support NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) Chipset: Intel® C741 Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port(s) USB: 2 USB 3.2 Gen1 Type-A port(s) (rear) 2 USB 2.0 Type-A port(s) (front) Video: 1 VGA port(s) Serial: 1 COM port(s) (Rear) TPM: 1 TPM header



Drive Bay	Description
1 - 6	2.5" Hot-swap PCIe 5.0 NVMe/SAS3/SATA3 Drive Bays

* NVMe or SAS3 support requires additional parts from the optional parts list



Slot	Slot Description
1 - 2	PCIe 5.0 x16 FHHL
3 - 4	PCIe 5.0 x16 AOM (OCP 3.0)

* Default Configuration. Exact slot quantity depends on the system loadout.

System Cooling	Fans: 6 middle cooling PWM 40x40x56mm Fan(s)
Power Supply	2x 800W/860W Redundant (1 + 1) Titanium Level power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); SuperDoctor® 5; Super Diagnostics Offline ; TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 8 Phase-switching voltage regulator FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 40 lbs (18.1 kg) Net Weight: 25 lbs (11.3 kg) Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X13SEDW-F
Chassis	CSE-LB16TS-R0AWNP3